



Final Product Change Notification

201705011F01

Issue Date: 23-Jul-2017
Effective Date: 21-Oct-2017

Here's your personalized quality information concerning products Digi-Key purchased from NXP.
For detailed information we invite you to view this notification online



QUALITY

Management Summary

product assembly migration from Chipbond to ASEK.
Chipbond old site closure, on end Q2, 2017
ASEK qualification finished and passed for NX5P3090UK

Change Category

- | | | | | |
|--|---|--|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input checked="" type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |

NX5P3090UK Bumping Site transfer from ChipBond to ASEK

Details of this Change

NXP is pleased to announce product assembly migration from Chipbond to ASEK. Bumping process is same, "repassivation + plated UBM + ball drop", But the bumping/assemble center change to ASEK.
The Bumping process in ASEK has been released in 2016.

Specific qualification tests for bumping transfer has been done on NX5P3090UK parts and all pass.

old product flow:

SSMC(fab) -> Chip-bond (bumping) -> ATKH (WT) -> Chip-bond (assembly)

new product flow:

SSMC(fab) -> ASEK (bumping) -> ATKH (WT) -> ASEK(assembly)

Why do we Implement this Change

Chipbond old site closure, on end Q2, 2017

ASEK new site production start wk1714

Identification of Affected Products

Top side marking

Top side Marking on Chipbond material is '5', while ASE-K is 't'.

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 30-Aug-2017

Impact

no impact to the product's functionality anticipated.

no impact

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 22-Aug-2017.

Remarks

Product Qualification has been done and passed.

Product Quality Information Package has been updated and attached in this PCN.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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Affected Part Number

NX5P3090UKZ